

Introducing Fortis Zd Connector

KEY FEATURES

Allows 10 Gb/s+ data rates

Extreme mechanical and electrical performance for the most demanding applications

Modular design allows for user configurability and modular evolution

M55302 heritage Mini-Box separable interface provides 4 points of contact on all sides of the pin

Three shell varieties for application versatility, including plastic, shielded and machined metal shell

3-Pair and 2-Pair versions available to accommodate multiple slot pitches

Space compatible materials

Proven compliant pin board attach facilitates manufacturing efficiency, repairability, and superior electrical performance

Staggered daughtercard pin field supports 2 level maintenance

Protected pin field on backplane for reliability and durability

DESCRIPTION

Modular backplane connector system combining the highest performance mil/aero and commercial technologies in a user configurable platform.

Built to be the most robust and highest performance backplane connector.

APPLICATIONS

Commercial
Aerospace



Ground
Defense



Unmanned Aerial
Vehicles



Fighter Jets

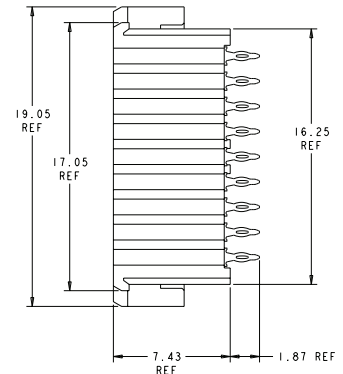
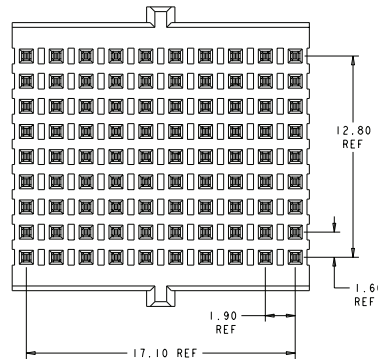


Severe mechanical environment applications, including terrestrial and outer space.

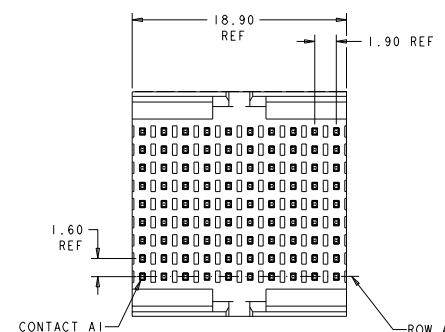
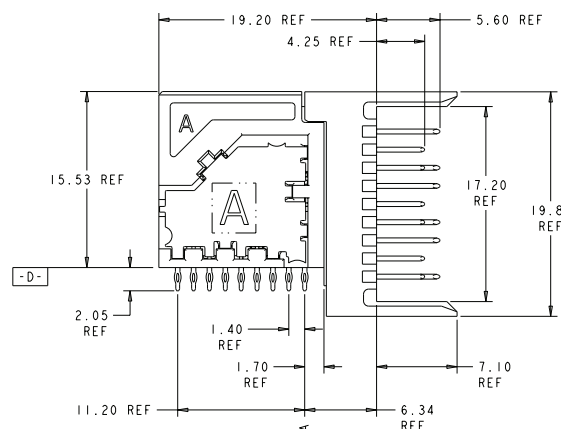
Motherboard/daughtercard applications in avionics, LRU/LRM and card cages.

PRODUCT DIMENSIONS

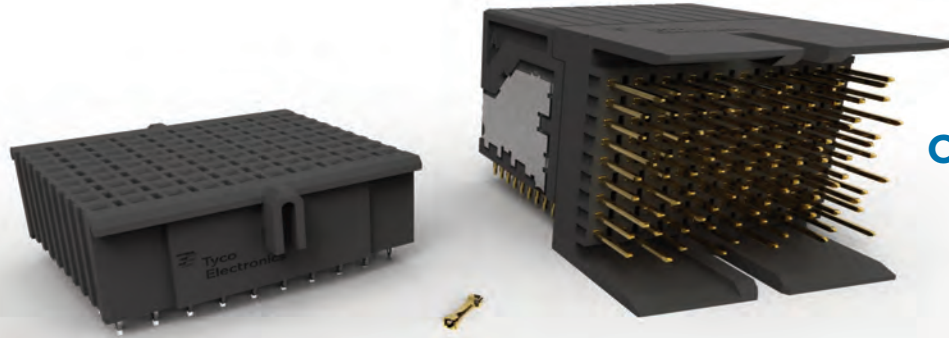
2000896-1 (3-pair, Vertical Center Module)



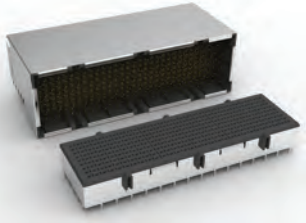
2000891-1 (3-pair, Right-Angle Center Module)



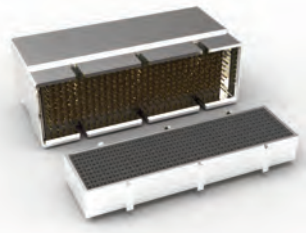
Fortis Zd Connector



ELECTRICAL

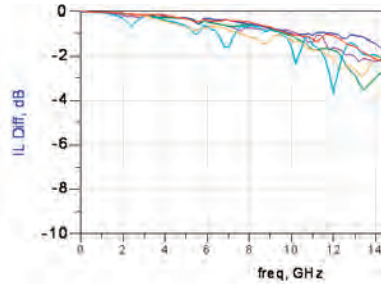


3-Bay Shielded

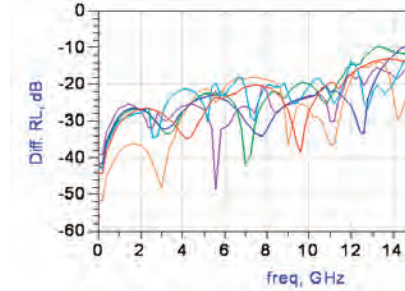


3-Bay Metal Shell

Differential Insertion Loss



Differential Return Loss



MECHANICAL

Durability:	500 mating cycles
Operating Temperature:	-55 to +125°C
Contact Engaging & Separating Force:	3 oz. typical

PHYSICAL OR OTHER PROPERTIES

- 10 and 20 column modules
- 3-pair (9-row) and 2-pair (6-row) modules
- 6U configuration offers 300 differential pairs
- Multi-bay shielded and metal shell options
- 6 row module enables 0.6" reduced form factor card pitch
- Modularity enables scalability for various card sizes

MATERIALS

Contacts:	High performance copper alloy Plated 50µ" Au over 50µ" Ni in mated contact area Tin/lead on compliant tails (gold or pure tin available)
Housings:	High temperature thermoplastic
Shell:	Shield: Copper alloy, Sn Pb plated Machined: Nickel plated 6061 Aluminum

APPLICATION TOOLING

Flat rock tooling

ORDERING INFORMATION

	Right-Angle Connector Modules						Vertical Connector Modules				
	10-column left	10-column center	20-column center	10-column right	10-column full shroud	20-column full shroud	10-column end	10-column center	20-column center	10-column full shroud	20-column full shroud
3-pair	200890	2000891	2000903	2000892	2102155	2102159	2000895	2000896	2000905	2102157	2102161

FOR MORE INFORMATION

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